IN THE SPECIFICATION:

Please replace the fourth full paragraph on page 4 with the following:

In the past decade, a manufacturing technique termed ~~"stereolithography",~~"stereolithography," also known as "layered ~~manufacturing",~~manufacturing," has evolved to a degree where it is employed in many industries.

Please replace the second full paragraph on page 12 with the following:

With continued reference to FIG. 6, stabilizers 50 that protrude too great a distance ~~54B~~54 from active surface 14 of semiconductor device 10 could prevent shorter conductive structures, such as solder bump 30B, from establishing a reliable electrical connection between a contact pad 12 of semiconductor device 10 and the corresponding test pad 40 of test substrate 20. Thus, stabilizers 50 preferably each extend between the planes of the surfaces 14 and 24 of semiconductor device 10 and test substrate 20 a distance 54 that is less than or equal to the distance 28 that the planes or surfaces 14 and 24 are spaced apart when conductive structures, such as solder bumps 30, connect contact pads 12 to test pads 40. Accordingly, stabilizers 50 will not prevent the shortest conductive structure, such as solder bump 30B, from connecting a contact pad 12 and a test pad 40 upon assembly of semiconductor device 10 with test substrate 20.

Please replace the paragraph bridging pages 21 and 22 with the following:

By way of example and not limitation, the layer thickness of material 86 to be formed, for purposes of the invention, may be on the order of about 0.0001 to 0.0300 inch, with a high degree of uniformity. It should be noted that different material layers may have different heights, so as to form a structure of a precise, intended total height or to provide different material thicknesses for different portions of the structure. The size of the laser beam "spot" impinging on the surface of material 86 to cure same may be on the order of 0.001 inch to 0.008 inch. Resolution is preferably ±0.0003 inch in the X-Y plane (parallel to surface 100) over at least a 0.5 inch × 0.25 inch field from a center point, permitting a high resolution scan effectively across a 1.0 inch × 0.5 inch area. Of course, it is desirable to have substantially this high a resolution

across the entirety of surface 100 of platform 90 to be scanned by laser beam 98, such area being termed the "field of ~~exposure",~~exposure," such area being substantially coextensive with the vision field of a machine vision system employed in the apparatus of the invention as explained in more detail below. The longer and more effectively vertical the path of laser beam 96/98, the greater the achievable resolution.

IN THE DRAWINGS:

The attached substitute drawing sheet includes corrections to FIG. 18. The substitute drawing sheet replaces the original sheet that included FIG. 18.